

ABSTRACT

A microstructured component having a layered construction may allow implementation of component structures having a layer thickness of more than 50 μm , e.g., more than 100 μm .

5 Capping of the component structure may allow vacuum enclosure of the component structure with a hermetically sealed electrical connection. The layered construction of the microstructured component includes a carrier including at least one glass layer, e.g., a Pyrex layer, a component
10 structure, arranged in a silicon layer, which is bonded to the glass layer, and a cap, which is positioned over the component structure and is also bonded to the glass layer.